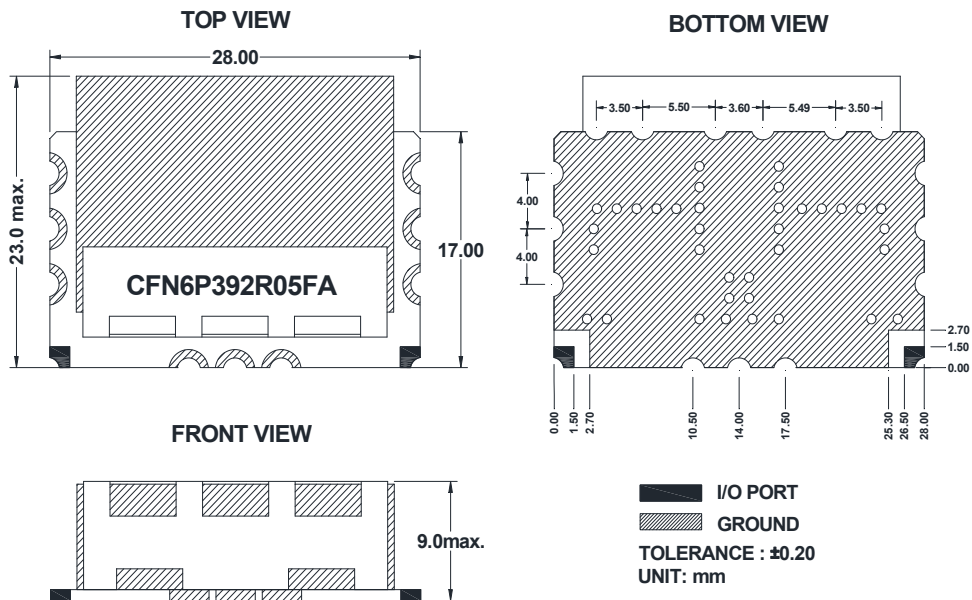


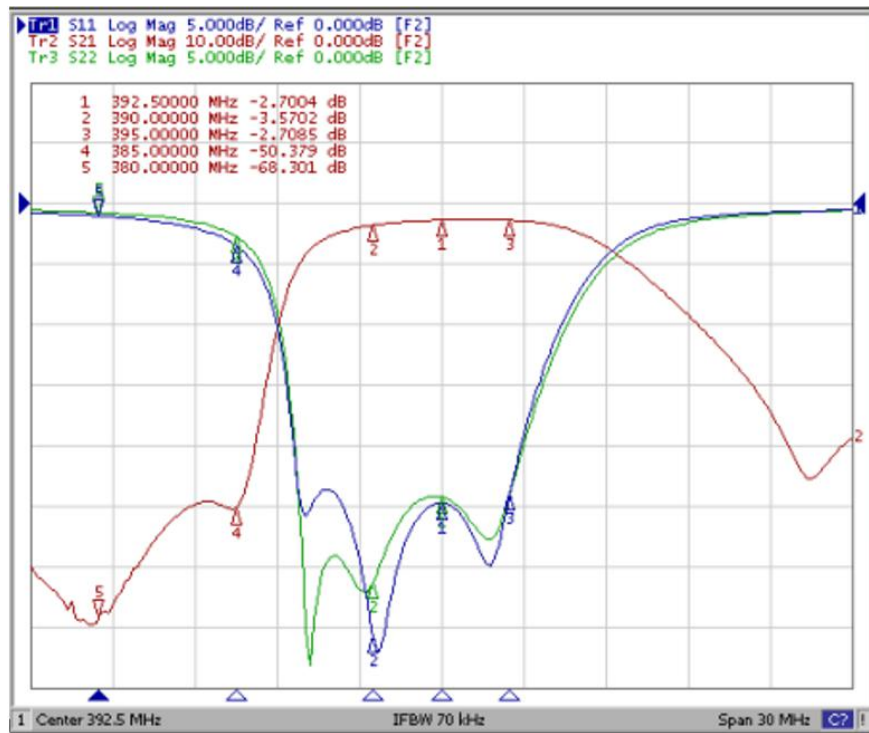
Electrical Specification

ITEMS	SPEC	UNIT
Center Frequency [fo]	392.5	MHz
Bandwidth [BW]	$f_o \pm 2.5$ [390.0 ~ 395.0]	MHz
Insertion Loss in BW	4.0	dB max
Ripple in BW	2.0	dB max
Return Loss in BW	10.0	dB min
Attenuation <input checked="" type="checkbox"/> Absolute Value <input type="checkbox"/> Relative Value	40.0 dB min. @ $f_o + 167.5$ [560.0 ~ 610.0]	MHz
	40.0 dB min. @ $f_o - 7.5$ [380.0 ~ 385.0]	MHz
	dB min. @ $f_o \pm$ [&]	MHz
	dB min. @ $f_o \pm$ [&]	MHz
Group Delay Variation		ns max
Input Power		W max.
In/Out Impedance	50 Ω	
Operation Temperature Range	-40°C to +85°C	

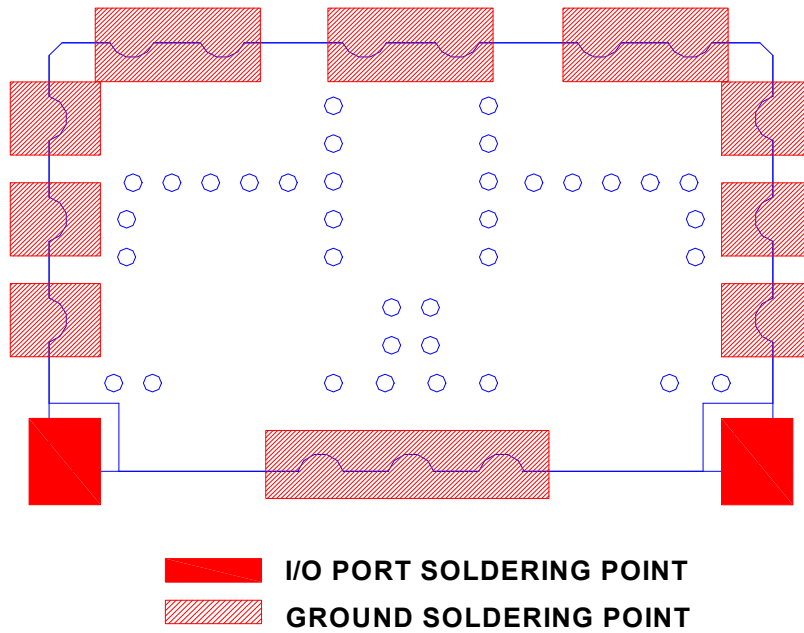
Mechanical Specification



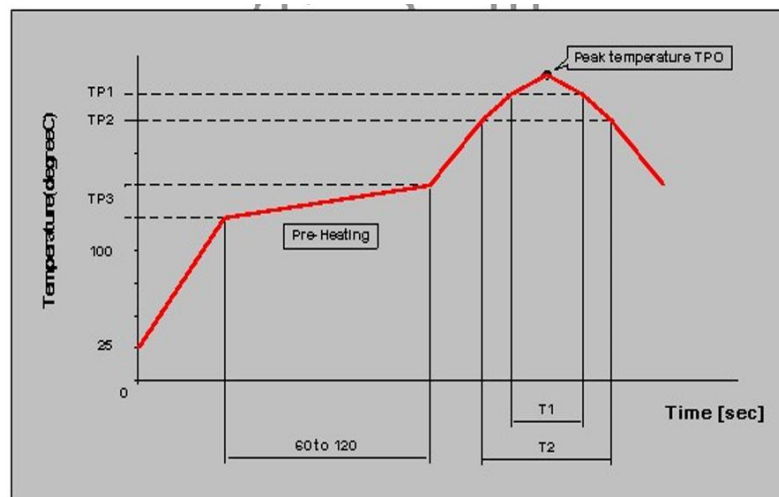
Plot Data



Recommended PC Board Pattern



Soldering Condition



Measuring point of temperature : IN-OUT Terminals of The Device
 Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

Reflow standard condition	TPO (°C)	TP1 (°C)	T1 (s)	TP2 (°C)	T2 (s)	TP3 (°C)
Sn-3Ag-0.5 solder	245±5	220	30 to 60	—	—	150 to 180
Test condition of reflow heat resistance	260±5/0	240	20	220	70	150 to 180